



# CIRRUS LOGIC® Process Change Notification

PCN Number: PCN-2015-23

PCN Notification Date: 8/7/2015

## Informational PCN WM8998 Carrier tape change

Dear Customer,

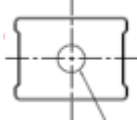
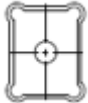
This notification is to advise you of the following change(s).

From 1<sup>st</sup> September 2015 onwards, Cirrus Logic will transition WM8998 product from Carrier tape KS-1208-810 to Carrier tape CCA114-A.

CCA114-A carrier tape has increased relief areas in pocket corners to improve the robustness of the carrier tape and reduce the risk of mechanical damage during shipment.

Drop test results for this carrier tape have been performed with 100% pass result.

Some mechanical setup changes will be required in SMT to accommodate this new tape. Details are shown below:

	KS1208-810	CCA114-A
A0	5.64 +/-0.1mm	4.33 +/-0.05mm
B0	4.38 +/-0.1mm	5.74 +/-0.05mm
C0	0.8 +/-0.1mm	0.78 +/-0.1mm
		

If you have any questions, please contact your Sales Representative.

Sincerely,

Quality Systems Administrator  
Cirrus Logic Corporate Quality  
Phone: +1(512) 851-4000



# CIRRUS LOGIC Process Change Notification

PCN Number: PCN-2015-23

PCN Notification Date: 8/7/2015

## Products Affected:

The devices listed on this page are the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

Technical details of this Process / Product Change follow on the next page(s).

<b>Title:</b>		WM8998 Carrier tape change			
<b>Customer Contact:</b>		N/A		<b>Phone:</b>	<b>Dept:</b>
<b>Proposed 1<sup>st</sup> Ship Date:</b>		09 2015		<b>Estimated Sample Availability Date:</b> 08 2015	
<b>Change Type:</b>					
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Process	<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Process	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Design
<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Part Number
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Other	<input type="checkbox"/>	
<b>Comments:</b>					

PCN Details					
<b>Description of Change:</b>					
Carrier tape modified with increased relief areas in pocket corners to improve the mechanical robustness of the carrier tape during product shipments.					
<ul style="list-style-type: none"> <li>Change Type Here: From: KS-1208-810 To: CCA114-A</li> </ul>					
<b>Reason for Change:</b>					
To improve the mechanical robustness of the carrier tape.					
<b>Anticipated Impact on Form, Fit, Function, Quality or Reliability:</b>					
Improved quality by implementing new tape design to improve the mechanical robustness and reduce risk of mechanical damage during the shipping process.					
<b>Product Affected:</b>					
<table border="1"> <thead> <tr> <th>Device</th> <th>Cirrus Logic Part Number</th> </tr> </thead> <tbody> <tr> <td>1</td> <td>WM8998ECS/R</td> </tr> </tbody> </table>		Device	Cirrus Logic Part Number	1	WM8998ECS/R
Device	Cirrus Logic Part Number				
1	WM8998ECS/R				



# CIRRUS LOGIC Process Change Notification

PCN Number: PCN-2015-23

PCN Notification Date: 8/7/2015

### Changes To Product Identification Resulting From This PCN:

No change

### Qualification Data:

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

**Qualification Schedule**

**Start:**

03 2015

**End:**

03 2015

### Qualification Device Construction Details

Detail Description	Device 1	Device 2
<b>Part Number(s):</b>	WM8998ECS/R	
<b>Wafer Fab Site Code/Name:</b>	F5 / TSMC Fab5 (Taiwan)	
<b>Wafer Technology:</b>	152 nm	
<b>Die Size:</b>	5.31 x 4.05 mm	
<b>Assembly Site Code/Name:</b>	ATT5 / Amkor T5 (Taiwan)	
<b>Package Type/Code:</b>	WLCSP	
<b>Moisture Level:</b>	MSL1	
<b>Package Pins:</b>	117 ball	
<b>Lead Frame Material:</b>	N/A	
<b>Mold Compound Supplier:</b>	N/A	
<b>Lead Finish:</b>	N/A	
<b>Die Attach Material</b>	N/A	
<b>Wire Diameter:</b>	N/A	
<b>Wire Base Metal:</b>	N/A	



# CIRRUS LOGIC Process Change Notification

PCN Number: PCN-2015-23

PCN Notification Date: 8/7/2015

The Qualification Plans are designed using JEDEC and other applicable industry standards. An overall summary of the Qualification results will be submitted upon completion.

## WM8998ECS/R Qualification

WM8998ECS/R Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results			
Reliability Test			Sample Size (PASS/FAIL)
<b>DT</b> (Drop test)	ISTA 2A 2008	One reel of 4,500 parts reeled with new carrier tape, packed within one shipping carton dropped on 1 corner, 3 edges, and 6 faces. 100% inspection post drop test.	4500 / <b>0 fail</b>
<b>PS</b> (Peel strength test)	EIA 481, IEC 286-3	3 strips of new carrier tape (minimum length 240mm) sealed with cover tape. 100% inspection to check for delamination of cover tape from carrier tape	3 / <b>0 fail</b>
<b>TTM</b> (Twist test method)	EIA 481, IEC 286-3	30cm of sealed tape subjected to twist stress testing. 100% inspection post-test to check for delamination of cover tape from carrier tape.	1 / <b>0 fail</b>
<p><b>Notes:</b></p> <ul style="list-style-type: none"> <li>Qualification tests "pass" on zero fails for each test</li> </ul> <p><b>Reliability Qualification Results:</b></p> <p>N/A</p>			